

PART NUMBER

74LS384N-ROCV

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All re-creations are done with the approval of the Original Component Manufacturer. (OCM)

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceeds the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-38535
 - Class Q Military
 - Class V Space Level

Qualified Suppliers List of Distributors (QSLD)

• Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OCM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.



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- Two's-Complement Multiplication
- Magnitude Only Multiplication
- Cascadable for Any Number of Bits
- 8-Bit Parallel Multiplicand Data Input
- Serial Multiplier Data Input
- Serial Data Output for Multiplication
 Product
- 40 MHz Typical Maximum Clock Frequency

description

The 'LS384 is an 8-bit by 1-bit sequential logic element that performs digital multiplication of two numbers represented in two's-complement form to produce a two's-complement product without external correction by using Booth's algorithm internally. The device accepts an 8-bit multiplicand (X input) and stores this data in eight internal latches. These X latches are controlled via the clear input. When the clear input is low, all internal flip-flops are cleared and the X latches are opened to accept new multiplicand data. When the clear input is high, the latches are closed and are insensitive to X input changes.

The multiplier word data is passed by the Y input in a serial bit stream, least significant bit first. The product is clocked out the PROD output, least significant bit first.

SN74LS384	· J PACKAGE · N PACKAGE P VIEW)
CLR 1	16 VCC
X3 2	15 Y
X2 3	14 X4
X1 4	13 X5
X0 5	12 X6
PROD 6	11 X7
CLK 7	10 K
GND 8	9 MODE



NC - No internal connection

The multiplication of an m-bit multiplicand by an n-bit multiplier results in an (m + n)-bit product. The 'LS384 must be clocked for m + n clock cycles to produce this two's complement product. The n-bit multiplier (Y-input) sign bit data must be extended for the remaining m bits to complete the multiplication cycle.

The device also contains a K input so that devices can be cascaded for longer length X words. The PROD output of one device is connected to the K input of the succeeding device when cascading. The mode input is used to indicate which device contains the most significant bit. The mode input is wired high or low depending on the position of the 8-bit slice in the total X word length. The device with the most significant bit is wired low and all lower order bit packages are wired high.

The SN54LS384 will be characterized for operation over the full military temperature range from -55° C to 125° C. The SN74LS384 will be characterized for operation from 0° C to 70° C.



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FUNCTION TABLE

	INPU	ITS		INTERNAL	OUTPUT	FUNCTION				
CLR	CLK	Xi	Y	Y_1	PROD	FONCTION				
L	х	Data	х	L	L	Load new multiplicand and clear internal sum and carry registers				
Н	1	Х	L	L	Output	Shift sum register				
н	1	Х	L	Н	per	Add multiplicand to sum register and shift				
Н	1	Х	Н	L	Booth's	Subtract multiplicand from sum register and shift				
Н	1	Х	н	Н	algorithm	Shift sum register				

H = high-level, L = low-level, X = irrevelant, \uparrow = low-to-high-level transition

schematics of inputs and outputs



logic symbol[†]



[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for J and N packages.



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1) .		V
	5.5 \	
Operating free-air temperature range:	SN54LS384	С
	SN74LS384 0°C to 70°	С
Storage temperature range	-65°C to 150°	С

NOTES: 1. Voltage values are with respect to network ground terminal.

2. Input voltages must be zero or positive with respect to network ground terminal.



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recommended operating conditions

		SN54LS384			SN74LS384			LINUT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	V	
High-level output current, IOH				400			-400	μA	
Low-level output current, IOL				4			8	mA	
Clock frequency, fclock		0		25	0		25	MHz	
Setup time, t _{su}	Y before Clock ↑	45			38			ns	
	K before Clock 1	30			24				
	X before Clear 1	23			19				
Clear inactive-state set up time befo	pre Clock 1	30			20				
	Y after Clock ↑	0			0				
Hold time, t _h	K after Clock 1	0			0			ns	
	X after Clear †	2			2			1	
·····	Clock high	20			20				
Pulse width, tw	Clock low	20			20			ns	
	Clear low	38			33			1	
Operating free-air temperature, TA	Derating free-air temperature, TA			125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS [†]		SN54LS384			SN74LS384				
_	PARAMETER	(TEST CONDITIONS'			MIN	TYP‡	MAX	MIN	τγρ‡	MAX	UNIT
VIH	High-level input v	oltage				2			2			V
VIL	Low-level input v	oltage						0.7			0.8	V
VIK	Input clamp volta	ige	$V_{CC} = MIN,$	l _l = –18 mA				-1.5			-1.5	V
vон	VOH High-level output voltage		V _{CC} = MIN, VIL = VIL max,		μA	2.5	3.4		2.7	3.4		v
N	VOL Low-level output voltage		V _{CC} = MIN,	V1H = 2 V,	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	v
VOL			VIL = VIL max		IOL = 8 mA					0.35	0.5	v
I ₁	Input current at n input voltage	naximum	V _{CC} = MAX,	V _I = 5.5 V	• · · · · · · · · · · · · · · · · · · ·			1			1	mA
	X, Mode	X, Mode	V _{CC} ≈ MAX, V _I =					20			20	
1	High-level	K, Clear		V ₁ = 2.7 V				30			30	
ίн	input current	Clock						40			40	μA
		Y						80			80	
	X, Mode	X, Mode						-0.48			-0.48	
1	Low-level K, Clear			$\lambda = 0.4 \lambda $	- 0.4.14			-1.2			-1.2	
ΠĽ	input current	Clock	V _{CC} = MAX,	V _I = 0.4 V				-1.6			-1.6	mA
		Y						3.2			-3.2	
los	OS Short-circuit output current §		V _{CC} = MAX			20		-100	-20		-100	mA
ICC	Supply current		V _{CC} = MAX,	See Note 3			91	132		91	132	mA

[†]For conditions shown at MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 3: I_{CC} is measured with the clear input grounded and all other inputs and outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax	Maximum clock frequency		25	40	2.2	MHz
tPLH	Propagation delay time, low-to-high-level output from clock	$C_{L} = 15 pF$,		15	23	ns
^t PHL	Propagation delay time, high-to-low-level output from clock	$R_{L} = 2 k\Omega$,		15	23	ns
^t PHL	Propagation delay time, high-to-low-level output from clear	See Note 4		17	25	ns

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

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TYPICAL APPLICATION DATA

FIGURE 1-BASIC 24-BIT SERIAL/PARALLEL CONNECTION



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FIGURE 2-8-BIT BY 8-BIT MULTIPLIER, BUS ORGANIZED, WITH 8-BIT TRUNCATED PRODUCT



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